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Application Serial No: 10/564,114
Responsive to the final Office Action mailed on: May 22, 2009

IN THE SPECIFICATION

Amendments to the Specification:

Please amend the following at page 4, lines 16-17 of the specification:

[0013] [FIG. 1 FIGS. 1A-1B] FIG. 1 FIG. 1A is a schematic sectional view showing a module according to Embodiment 1 of the present invention and FIG. 1B is a schematic view showing one embodiment of a first radio communication element.

Please amend the following at page 10, lines 21-30 of the specification:

First, a module according to Embodiment 1 of the present invention will be described with reference to the accompanying drawings. FIG. 1 FIG. 1A to be referred to is a schematic sectional view showing the module according to Embodiment 1. FIG. 2 to be referred to is a plan view, seen from a substrate side, schematically showing a semiconductor package included in the module according to Embodiment 1.

[0031] As shown in FIG. 1 FIG. 1A, a module 1 according to Embodiment 1 has a substrate 12 and a plurality of semiconductor packages 11a, 11b ... (in the following, simply referred to as "the semiconductor packages 11a, 11b"), each including a semiconductor chip 10, mounted on the substrate 12.

Please amend the following at page 11, lines 7-28 of the specification:

[0033] Further, each of the semiconductor packages 11a, 11b includes a first radio communication element 16 for transmitting and receiving a signal between the semiconductor chips 10 in the semiconductor packages 11a, 11b by radio communication (see FIG. 1B). This first radio communication element 16 is connected electrically to the semiconductor chip 10 via electrically conductive portions 17 formed of an electrically conductive material such as copper or solder. In the case of transmitting and receiving the signal between the semiconductor chips 10 included respectively in the semiconductor packages 11a, 11b, the signal is transmitted and received by radio communication between the first radio communication element 16 included in the semiconductor package 11a and the first radio communication element 16 included in the semiconductor package 11b. In other words, the signal is transmitted and received

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between the semiconductor chips 10 by radio communication via the first radio communication elements 16. Also, the signal is transmitted and received between the semiconductor chips 10 included respectively in the semiconductor packages that are not adjacent to each other in the module 1 (not shown) similarly to the above. This makes it possible to reduce the number of wirings, so that the module 1 can be miniaturized. Incidentally, in order to ensure radio communication, it is preferable that the distance between the first radio communication elements 16 between which the signal is transmitted and received is not greater than 5 mm.

Please amend the following at page 12, line 25-page 13, line 1 of the specification:

First, a module according to Embodiment 1 of the present invention will be [0038] As shown in FIG. 2, a shielding layer 19 (a hatched portion in FIG. 2) for blocking electromagnetic waves is provided in a part of a surface of the first radio communication element 16 facing the substrate 12 (see FIG. 4 FIG. 1A). This makes it possible to reduce the noise due to electromagnetic waves and to input and output the electromagnetic waves through only the portion 16a without the shielding layer 19 in the first radio communication element 16, thereby transmitting and receiving only necessary electromagnetic waves.

Please amend the following at page 14, lines 1-6 of the specification:

Next, a module according to Embodiment 2 of the present invention will be described with reference to the accompanying drawings. FIG. 3 to be referred to is a sectional view schematically showing the module according to Embodiment 2. Constituent elements that are the same as those in FIG. 1-FIG. 1A are assigned the same reference signs, and the description thereof will be omitted.

Please amend the following at page 14, line 26-page 15, line 12 of the specification:

[0046] Further, each of the semiconductor packages 21a, 21b includes a first radio communication element 16 for transmitting and receiving a signal between the semiconductor chips 20 in the semiconductor packages 21a, 21b by radio communication. This first radio communication element 16 is electrically connected to

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the semiconductor chip 20b via electrically conductive portions 17. Thus, similarly to the above-described module 1 according to Embodiment 1 (see FIG. 1-FIG. 1A), the signal is transmitted and received between the semiconductor chips 20 included respectively in the semiconductor packages 21a, 21b by radio communication, so that wirings etc. can be omitted so as to allow the miniaturization of the module 2.

[0047] Further, the first radio communication element 16 is constituted independently of the semiconductor chip 20. Consequently, similarly to the above-described module 1 according to Embodiment 1 (see FIG. 1-FIG. 1A), the manufacturing cost of the module 2 can be reduced. Moreover, it also is possible to alleviate the influence of the noise due to electromagnetic waves exerted by radio communication carried out by the first radio communication element 16 on an internal circuit of the semiconductor chip 20.

Please amend the following at page 17, lines 17-26 of the specification:

Now, a mounted structure according to Embodiment 4 of the present invention will be described with reference to the accompanying drawings. FIG. 6 to be referred to is a schematic sectional view showing the mounted structure according to Embodiment 4. Constituent elements that are the same as those in FIG. 1-FIG. 1A are assigned the same reference signs, and the description thereof will be omitted.

Please amend the following at page 15, lines 17-26 of the specification:

Now, as Embodiment 5 of the present invention, the following description is directed to an example of using a combination of a plurality of the modules according to an embodiment of the present invention in a mobile phone. FIG. 7 to be referred to is a perspective view schematically showing a mobile phone in which a plurality of the modules according to an embodiment of the present invention are used. Further, FIG. 8 to be referred to is a perspective view schematically showing the state in which a plurality of the modules according to an embodiment of the present invention are combined and used in the mobile phone shown in FIG. 7. It should be noted that constituent elements other than a first radio communication element in each module are omitted in FIG. 8. Also, constituent elements that are the same as those in FIG. 1-FIG. 1A are assigned the same reference signs, and the description thereof will be omitted.

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Please amend the following at page 20, lines 9-21 of the specification:

Now, as Embodiment 5 of the present invention, the following description is directed to an example of using a combination of a plurality of the modules according to an embodiment of the present invention in a mobile phone. FIG. 7 to be referred to is a perspective view schematically showing a mobile phone in which a plurality of the modules according to an embodiment of the present invention are used. Further, FIG. 8 to be referred to is a perspective view schematically showing the state in which a plurality of the modules according to an embodiment of the present invention are combined and used in the mobile phone shown in FIG. 7. It should be noted that constituent elements other than a first radio communication element in each module are omitted in FIG. 8. Also, constituent elements that are the same as those in FIG. 1-FIG. 1A are assigned the same reference signs, and the description thereof will be omitted.